

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6701DxxxJR-G
Typical Mass: 320 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.925	Silicon	2900	7440-21-3
Leadframe	168.780	Copper	527400	7440-50-8
	0.135	Iron	400	7439-89-6
	0.034	Phosphorus	100	7723-14-0
	0.101	Silver	300	7440-22-4
Die attach	0.371	Silver	1200	7440-22-4
	0.063	Acryl resin	200	—
	0.029	Polybutadiene derivative	100	—
	0.019	Epoxy resin	100	—
Bonding wire	0.035	Gold	100	7440-57-5
Resin	125.201	Silica	391300	60676-86-0
	16.356	Epoxy resin	51100	—
	7.137	Phenol resin	22300	—
Plating	0.812	Tin	2500	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."